

CLAIMS

1. A film carrier tape for mounting an electronic part, comprising a long insulating film and a large number of wiring patterns formed on a surface of the insulating film, said wiring patterns being made of a
5 conductive metal, wherein:

the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each
10 surface of the wiring patterns is split and/or divided into plural sections.

2. A film carrier tape for mounting an electronic part, comprising a long insulating film and a large
15 number of wiring patterns formed on a surface of the insulating film, said wiring patterns being made of a conductive metal and at least two of said wiring patterns being arranged side by side in the width direction of the long insulating film, wherein:

20 the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each surface of the wiring patterns is split and/or divided into plural sections.

3. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein the solder resist layer is formed on each surface of the wiring patterns in such a manner that the solder resist layer is split and/or divided into 2 to 16 sections.

4. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein in each film carrier, a distance between one section and its adjacent section of the split or divided solder resist layer is in the range of 20 μm to 50 mm.

5. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein the long insulating film has a thickness of not more than 75 μm .

6. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein an area occupied by one film carrier is substantially the same as an area of an electronic part to be mounted on the film carrier tape.

7. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein an opposite surface to the surface of the insulating film where the wiring pattern of the film carrier for mounting an electronic part is formed is designed so that metal balls to be electrically connected outside the film carrier can be arranged.

8. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein the solder resist layer formed on the surface of the wiring pattern has an average thickness, except non-solder resist area, of 3 to 50 μm after curing.

9. The film carrier tape for mounting an electronic part as claimed in claim 1 or 2, wherein the solder resist layer is formed in a region of not less than 20% of the wiring patterns except the connecting terminal portions.